

Title (en)
TOUCH PANEL, PREPARING METHOD THEREOF, AND AG-PD-ND ALLOY FOR TOUCH PANEL

Title (de)
BERÜHRUNGSBILDSCHIRM, HERSTELLUNGSVERFAHREN DAFÜR UND AG-PD-ND-LEGIERUNG FÜR EINEN BERÜHRUNGSBILDSCHIRM

Title (fr)
PANNEAU TACTILE, PROCÉDÉ DE PRÉPARATION DE CELUI-CI, ALLIAGE D'AG-PD-ND POUR L'ÉCRAN TACTILE

Publication
EP 2984543 A4 20161207 (EN)

Application
EP 14782326 A 20140313

Priority

- KR 20130038625 A 20130409
- US 2014025250 W 20140313

Abstract (en)
[origin: WO2014168712A1] Provided is a touch panel comprising: a transparent substrate, a transparent conductive material disposed on the 5 substrate, and a Ag-Pd-Nd alloy layer disposed on the transparent conductive material. Provided are also a preparation method of the touch panel and a display comprising the touch panel. Provided are also a Ag-Pd-Nd alloy for touch panel, comprising: 97.9 to 99.2 weight % of Ag, 0.7 to 1.8 weight % of Pd, and 0.1 to 0.3 weight % of Nd, based on 100 weight % of the alloy.

IPC 8 full level
C22C 5/06 (2006.01); **C23C 14/18** (2006.01); **C23C 14/34** (2006.01); **G06F 3/041** (2006.01); **G06F 3/044** (2006.01); **G06F 3/045** (2006.01); **H05K 1/03** (2006.01); **H05K 1/09** (2006.01)

CPC (source: EP KR US)
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Citation (search report)

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- [A] WO 2012043189 A1 20120405 - DAINIPPON PRINTING CO LTD [JP], et al & US 2014036165 A1 20140206 - TAKAHASHI MASAHIRO [JP], et al
- [A] WO 2012173192 A1 20121220 - NITTO DENKO CORP [JP], et al & EP 2722853 A1 20140423 - NITTO DENKO CORP [JP]
- See references of WO 2014168712A1

Designated contracting state (EPC)
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DOCDB simple family (publication)
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